data sheet

Ceramic Ball Grid Array Package (CBGA)

Amkor's CBGAs incorporate the most advanced assembly processes and designs for today and tomorrow's cost/performance applications. This advanced IC package technology allows application and design engineers to optimize innovations while maximizing the performance characteristics of semiconductors (Si & GaAs). Amkor's CBGAs are designed for low inductance, improved thermal operation and enhanced SMT-ability. Custom performance enhancements, such as ground and power planes, are available for significant improvements in electrical response demanded by advancing electronics. Additionally, these CBGAs utilize industry proven, semiconductor grade materials for reliable, long-term operation while providing the user flexible design parameters. The CBGA is a ceramic substrate package. It consist of a ceramic substrate which is covered with a B-Staged epoxy lid or by encapsulating it.

Applications:

Semiconductor technologies find enhanced performance by using the integrated design features of Amkor's CBGAs. Microprocessors/controllers, ASICs, Gate Arrays, memory, DSPs and PC chip sets find Amkor's CBGA family to be an ideal package. Applications requiring improved portability, form-factor/size and high-performance such as cellular, wireless, PCMCIA cards, laptop PC's, video cameras, disc drives, power amplifiers and other similar products benefit from Amkor's CBGA attributes.

Features:

The CBGA offers a variety of features. From innovative designs and expanding package offerings, Amkor provides a platform from prototype-to-production.

CBGA

- · Flexible ball counts
- 10mm to 35mm body sizes
- 1.0, 1.27, 1.5mm ball pitch available
- Eutectic (63/37) solder balls
- Perimeter, stagger and full ball arrays
- Special packaging for memory available
- \leq 6 mil coplanarity
- Multi-layer, ground/power
- Cavity lid seal or encapsulation
- Full in-house design capability
- JEDEC MO-151 standard outlines
- High thermal conductive ceramic



